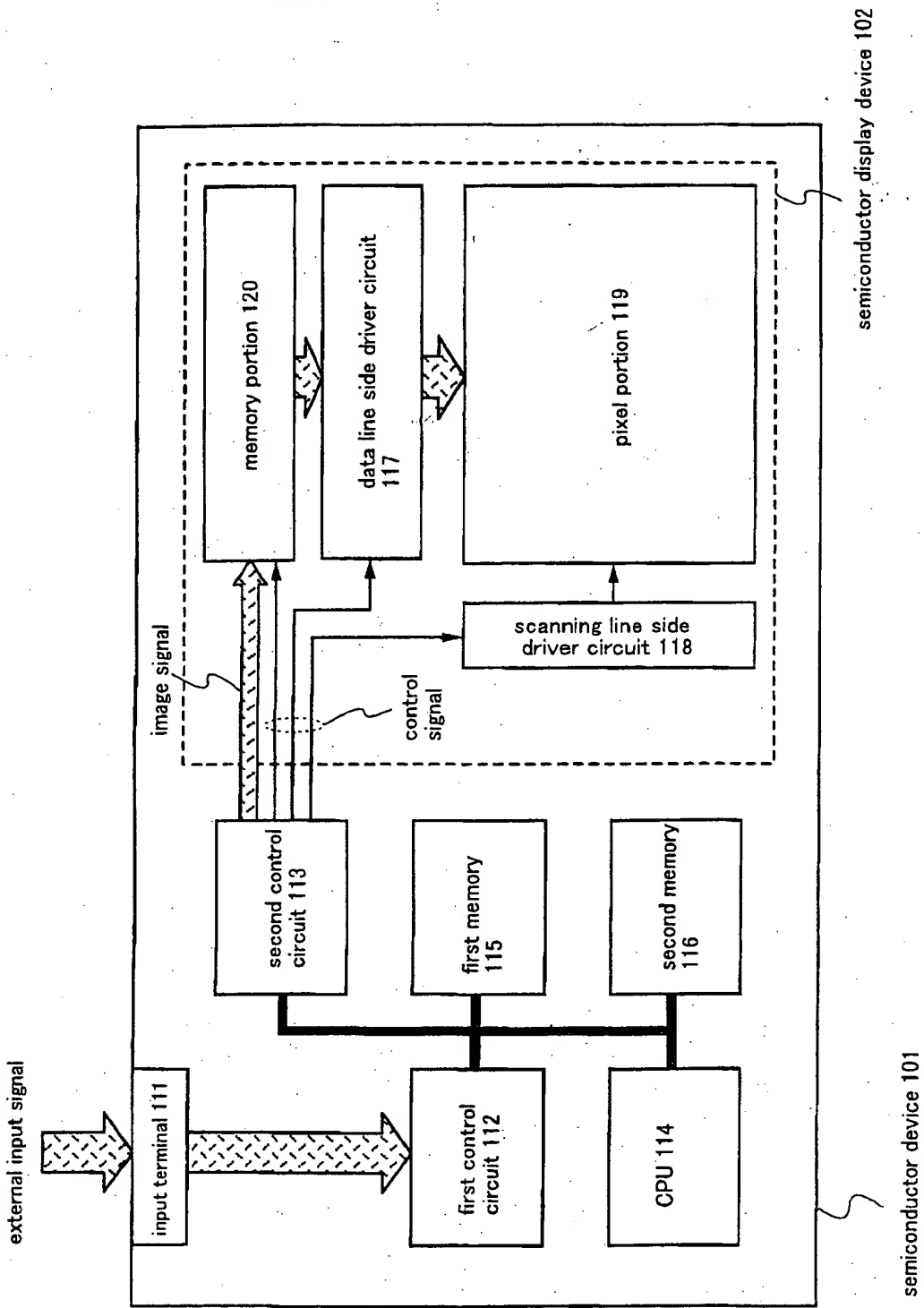
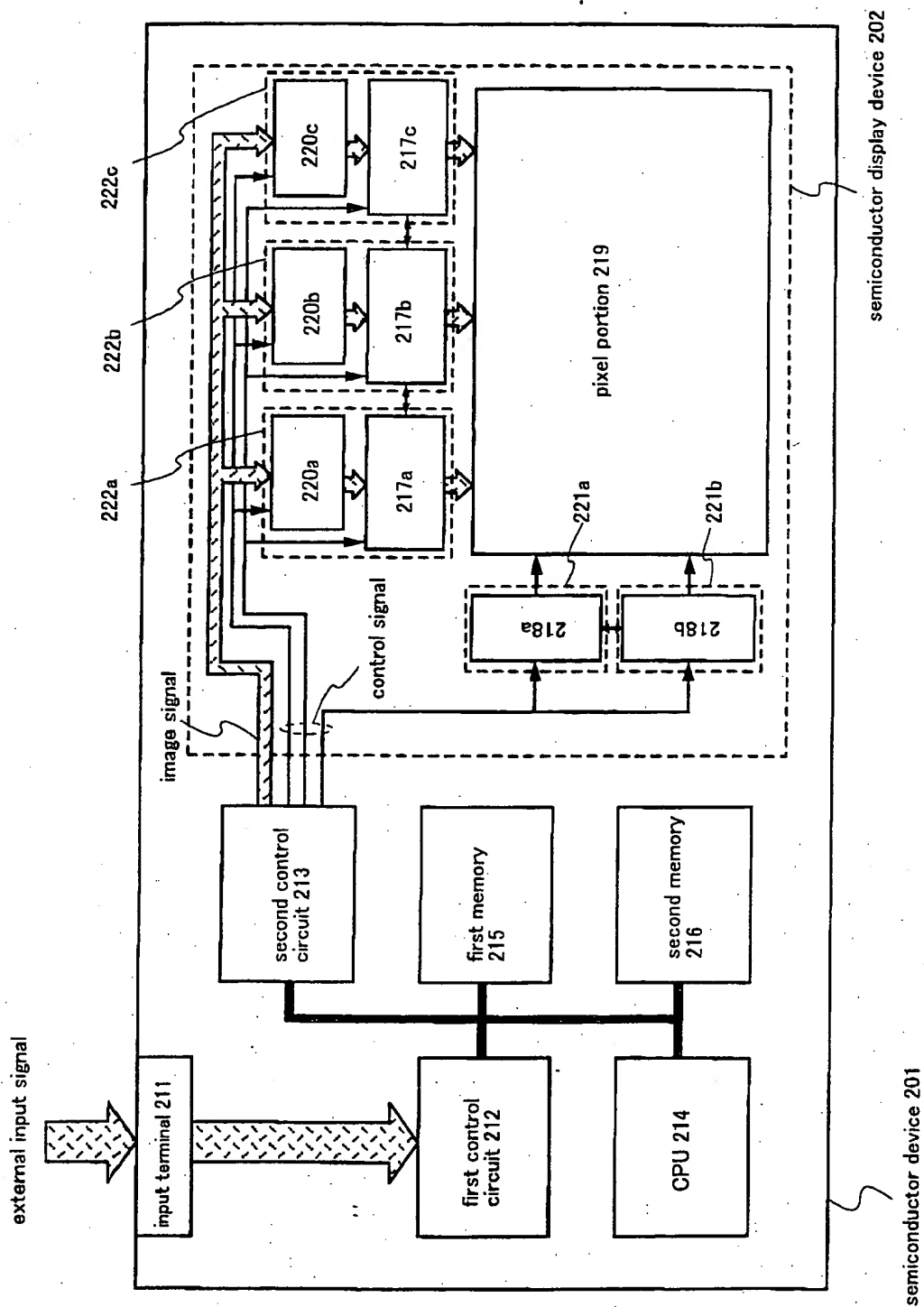


【Fig. 1】

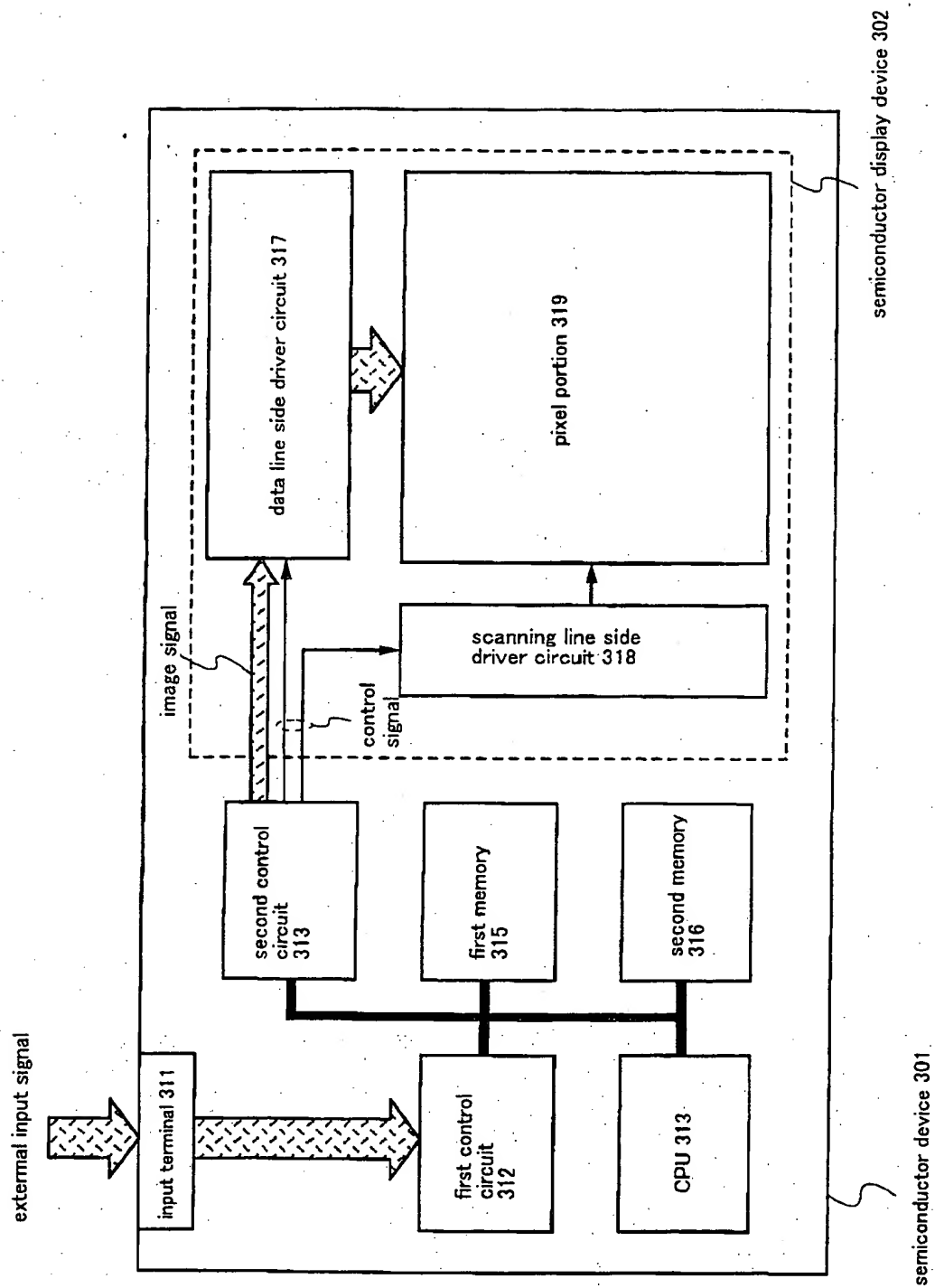


【Fig. 2】

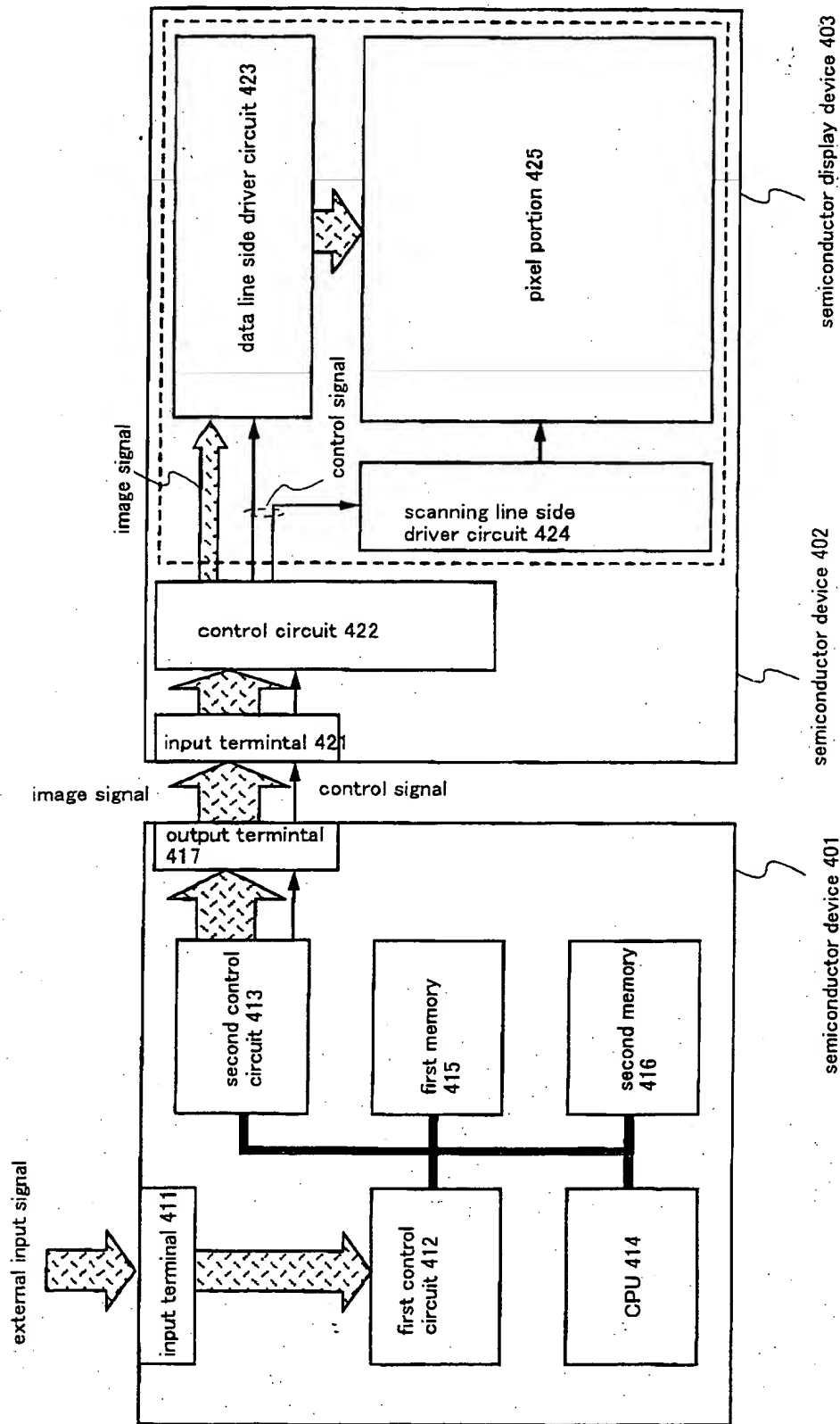


217a, 217b, 217c data line side driver circuit 218a, 218b scanning line side driver circuit
 220a, 220b, 220c memory portion 221a, 221b scanning line side stick driver
 222a, 222b, 222c data line side stick driver

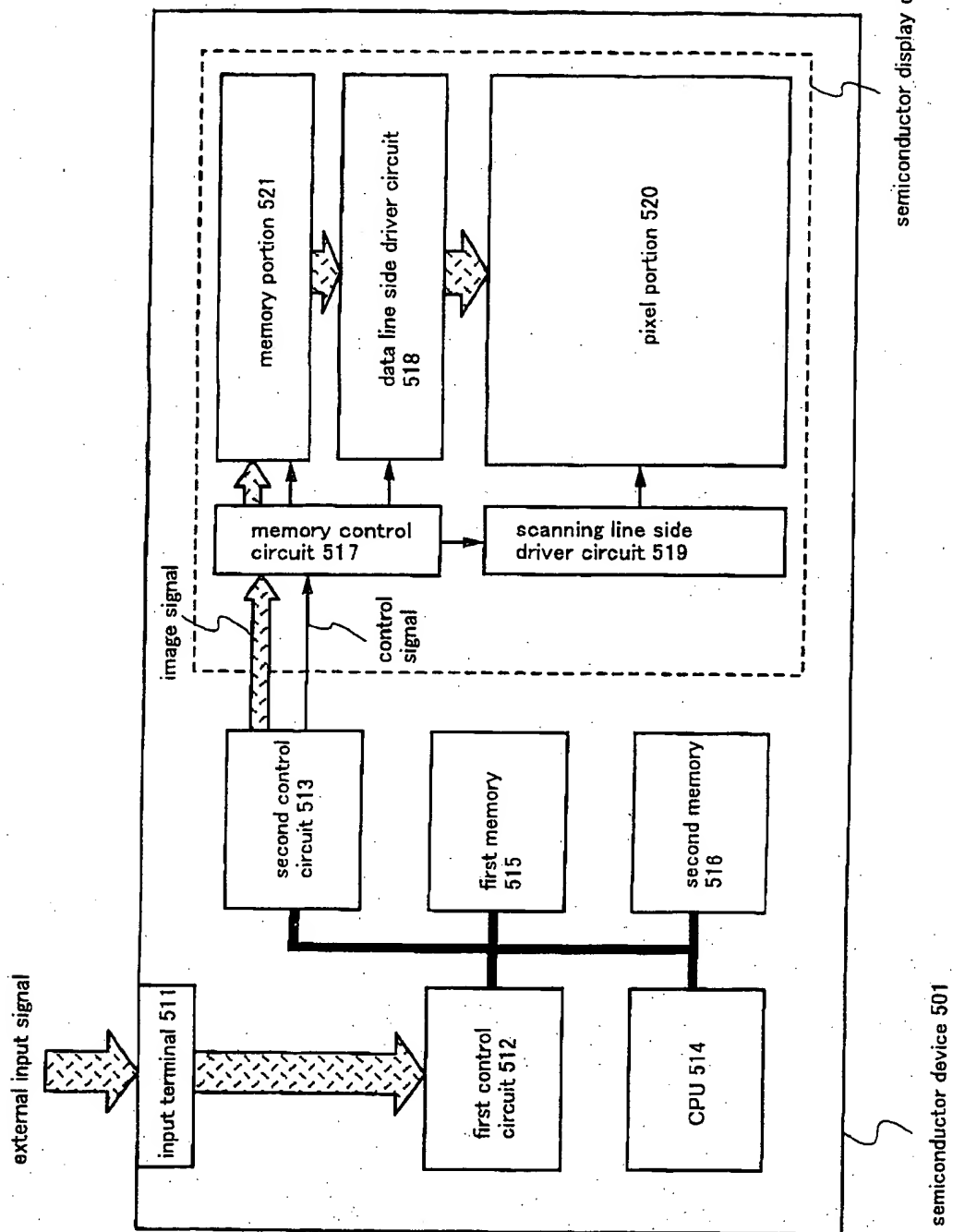
【Fig. 3】



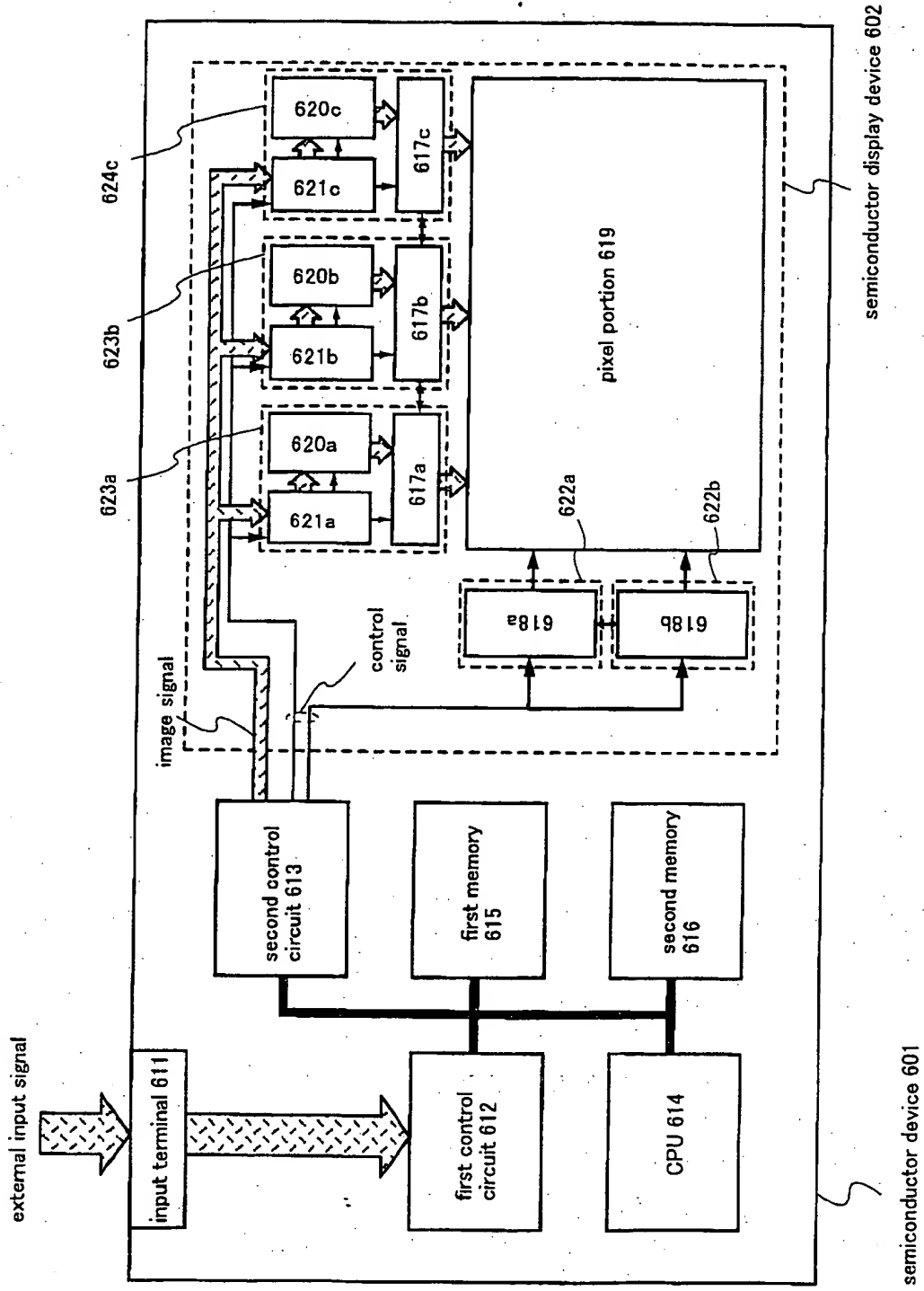
[Fig. 4]



[Fig. 5]

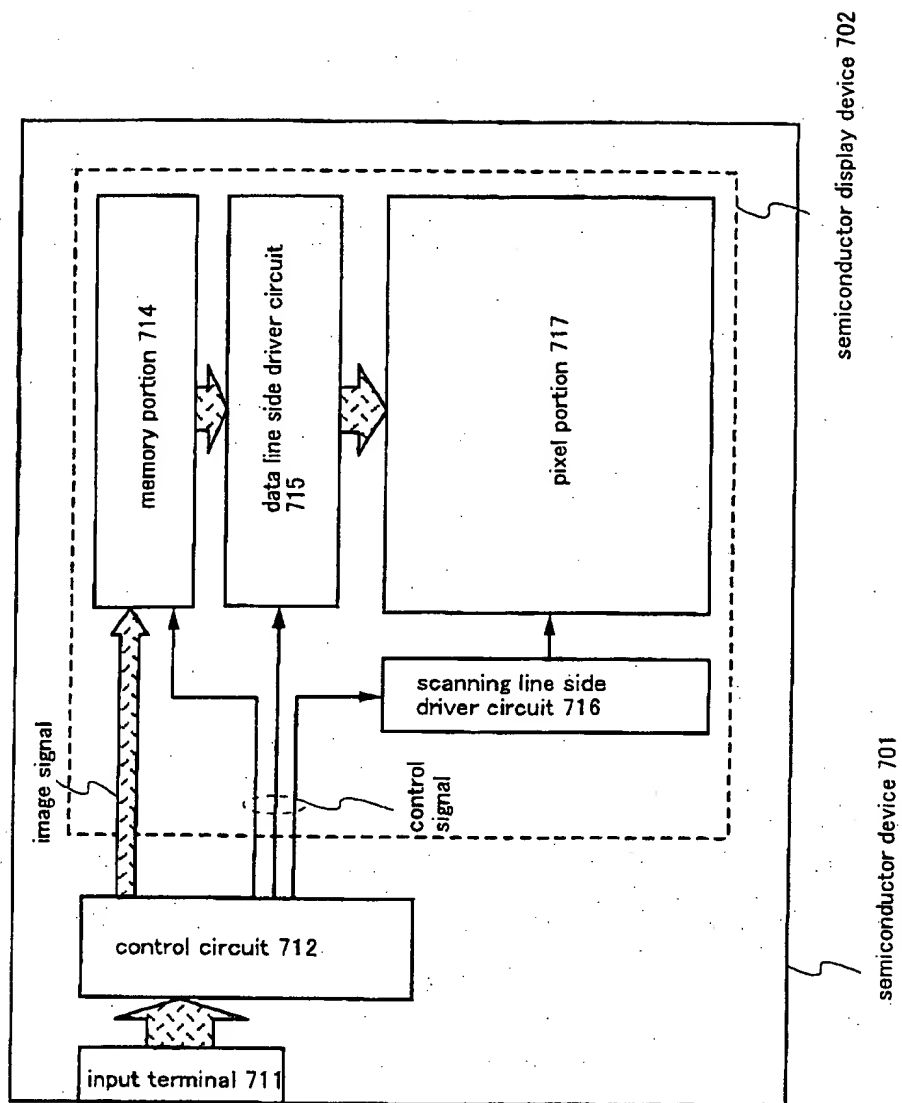


【Fig. 6】



617a, 617b, 617c data line side driver circuit 618a, 618b scanning line side driver circuit
 620a, 620b, 620c memory portion 621a, 621b, 621c memory control circuit
 622a, 622b scanning line side stick driver 623a, 623b, 623c data line side stick driver

【Fig. 7】



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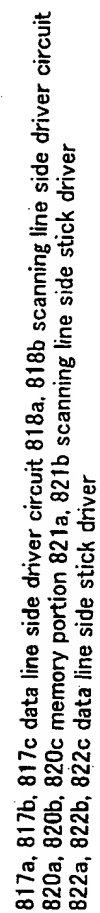


Fig. 9(A)

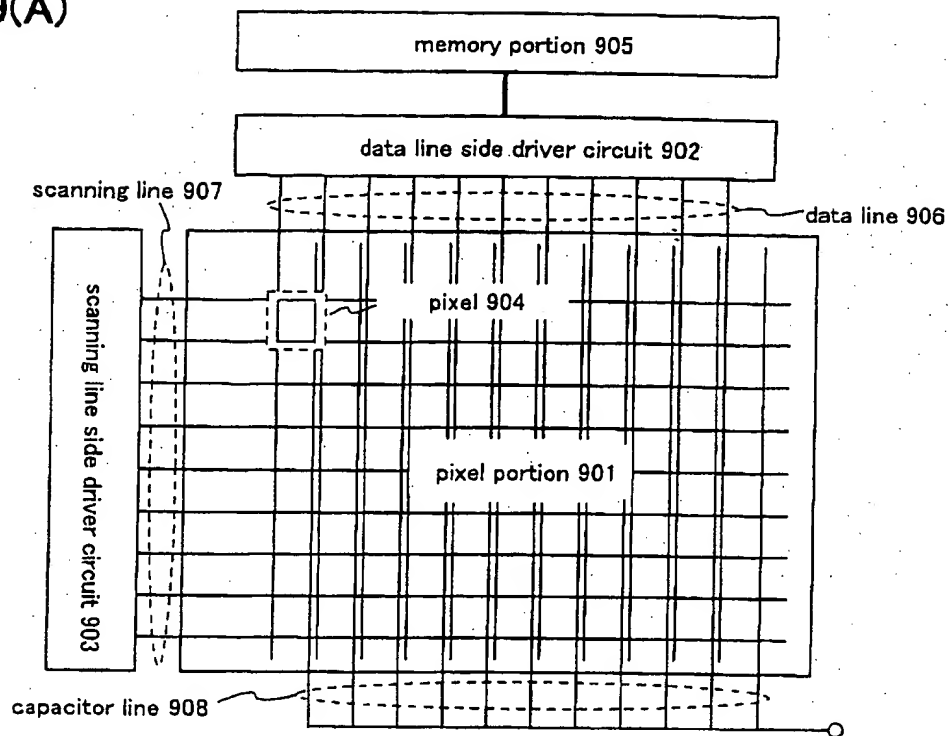
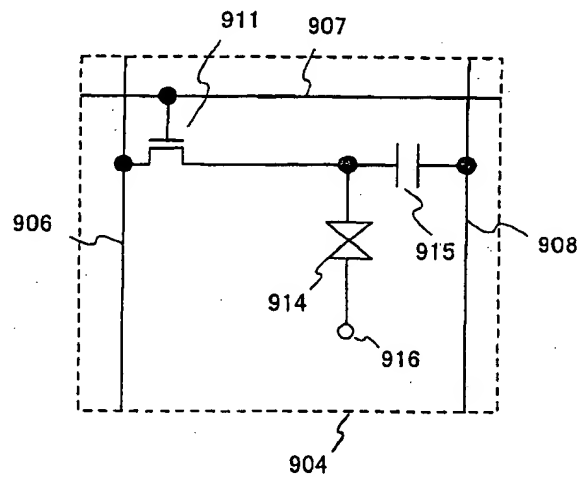


Fig. 9(B)



904 pixel 908 capacitor line 906 data line
 907 scanning line 911 switching TFT
 914 liquid crystal element 915 capacitor 916
 counter electrode

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Fig. 10 (A)

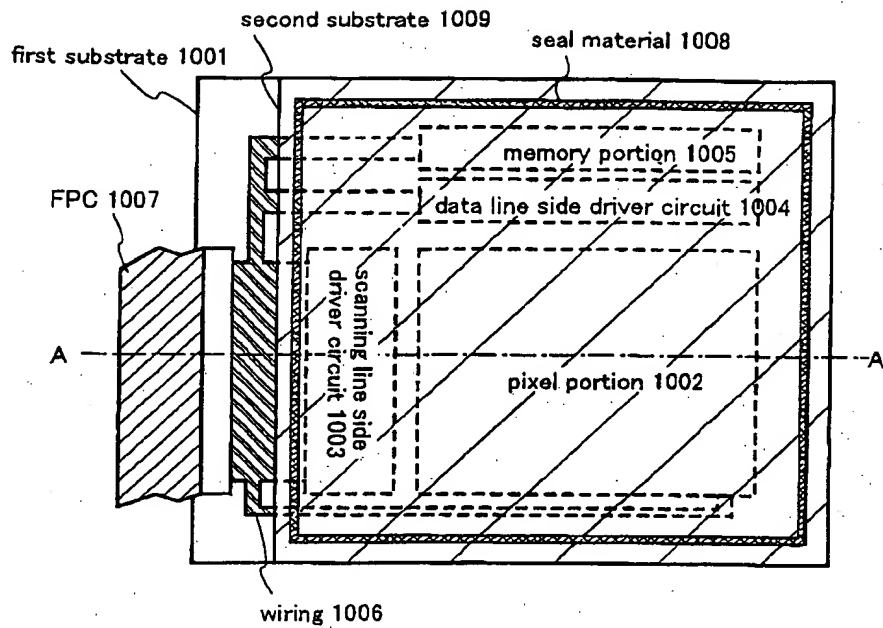
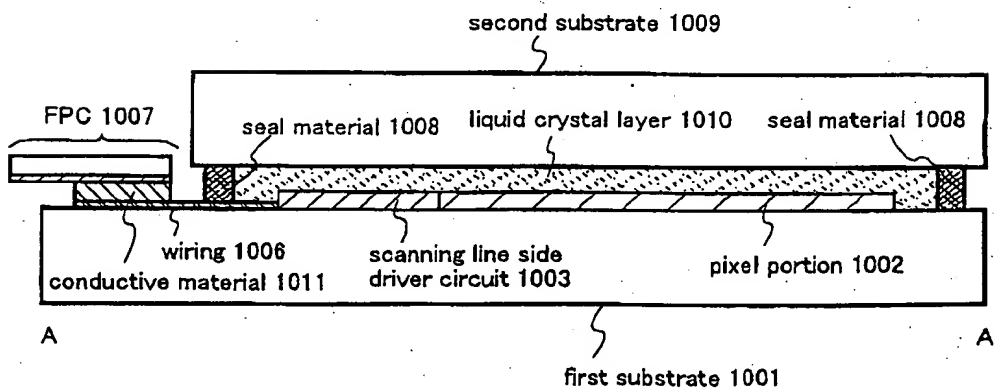
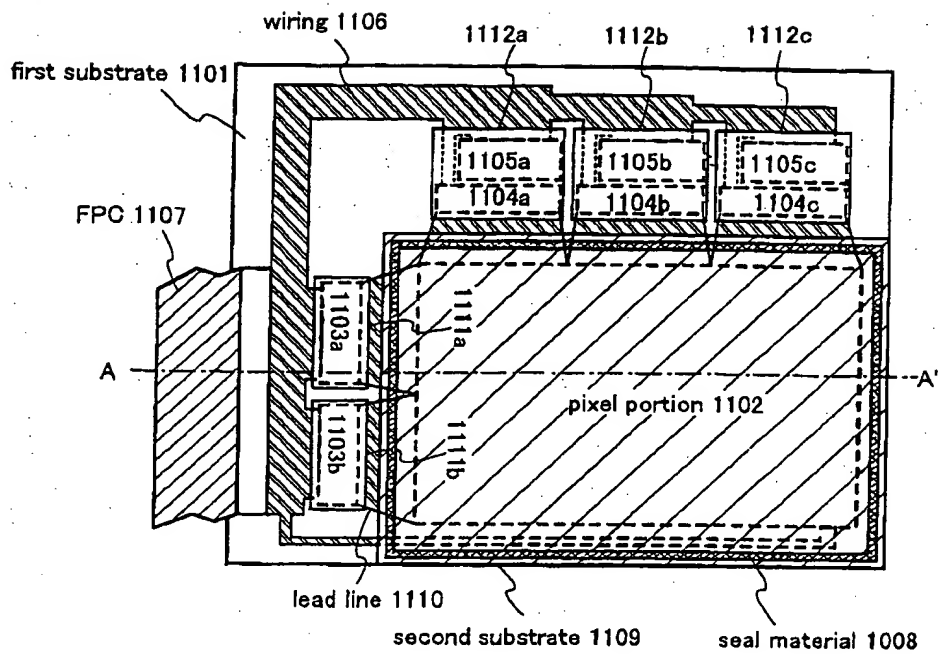


Fig. 10 (B)



09651433-100301

Fig. 11 (A)



1103a, 1103b scanning line side driver circuit
 1104a, 1104b, 1104c data line side driver circuit
 1105a, 1105b, 1105c memory portion
 1111a, 1111b scanning line side stick driver
 1112a, 1112b, 1112c data line side stick driver

Fig. 11 (B)

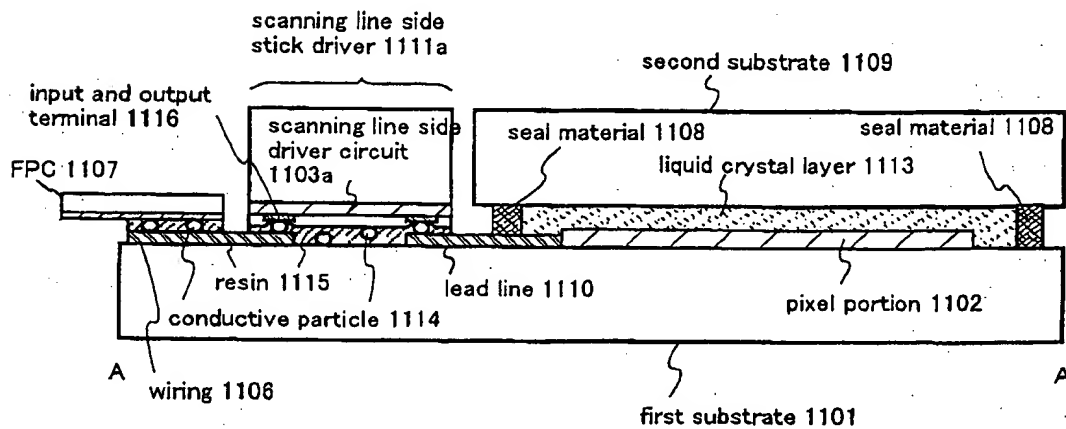


Fig. 12(A)

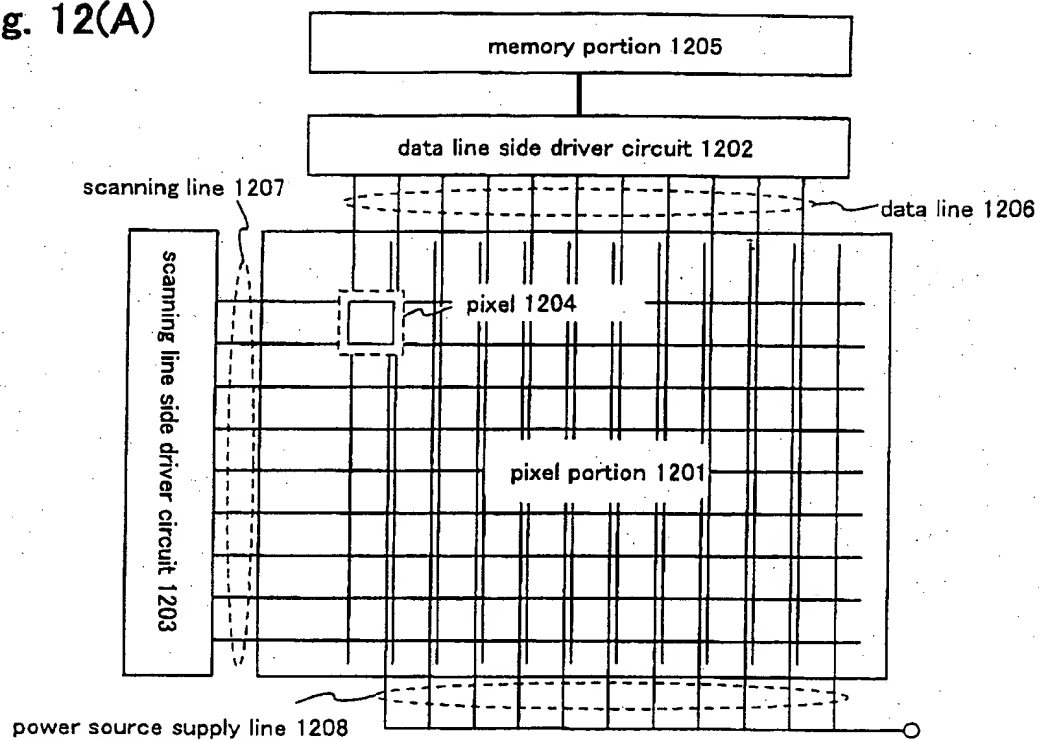
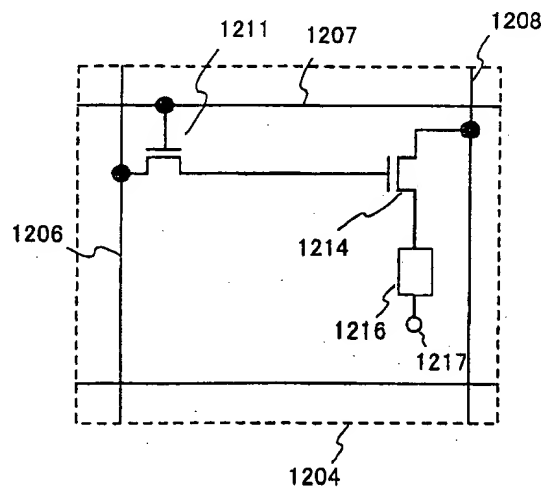


Fig. 12(B)



1204 pixel 1206 data line 1207 scanning line
1208 power source supply line 1211 switchin TFT
1214 EL driving TFT 1216 EL element 1217
counter electrode

Fig. 13(A)

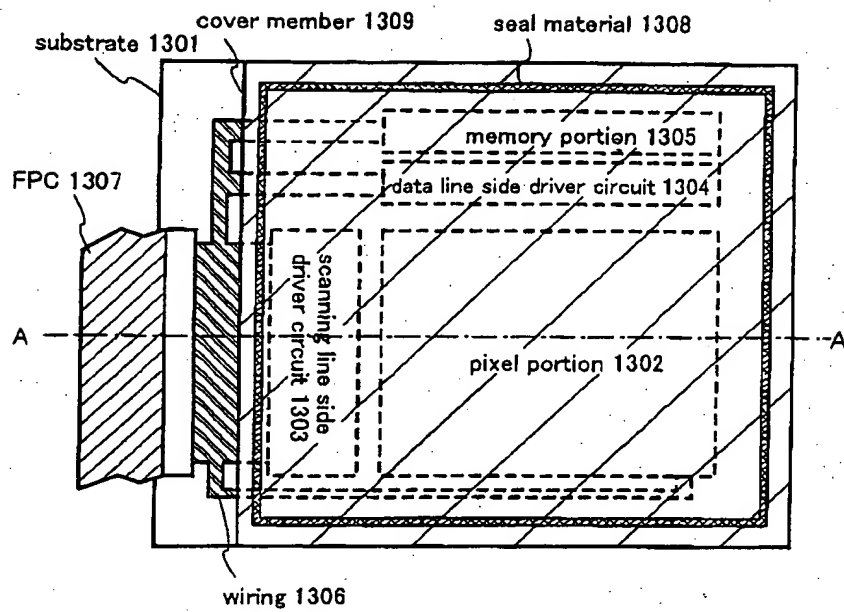


Fig. 13(B)

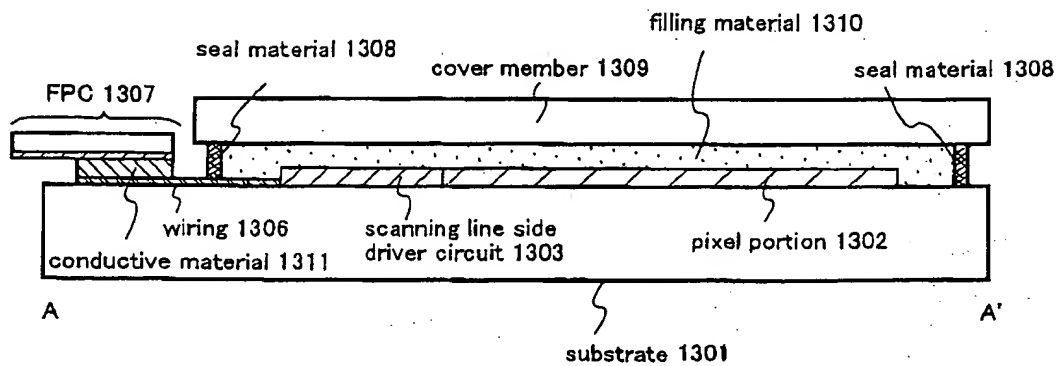
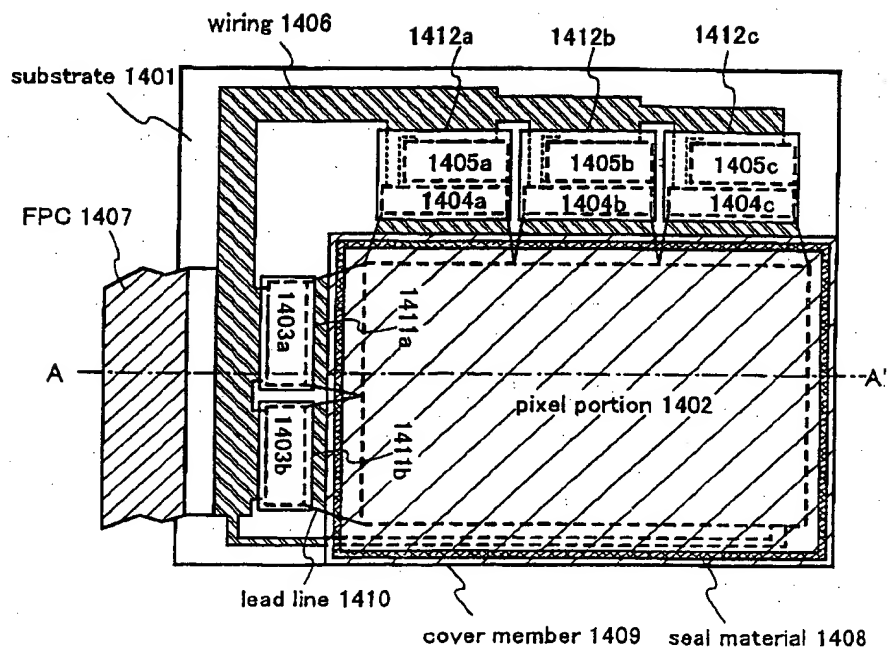


FIG. 13(A) 1000

Fig. 14(A)



1403a, 1403b scanning line side driver circuit
 1404a, 1404b, 1404c data line side driver circuit
 1405a, 1405b, 1405c memory portion
 1411a, 1411b scanning line side stick driver
 1412a, 1412b, 1412c data line side stick driver

Fig. 14(B)

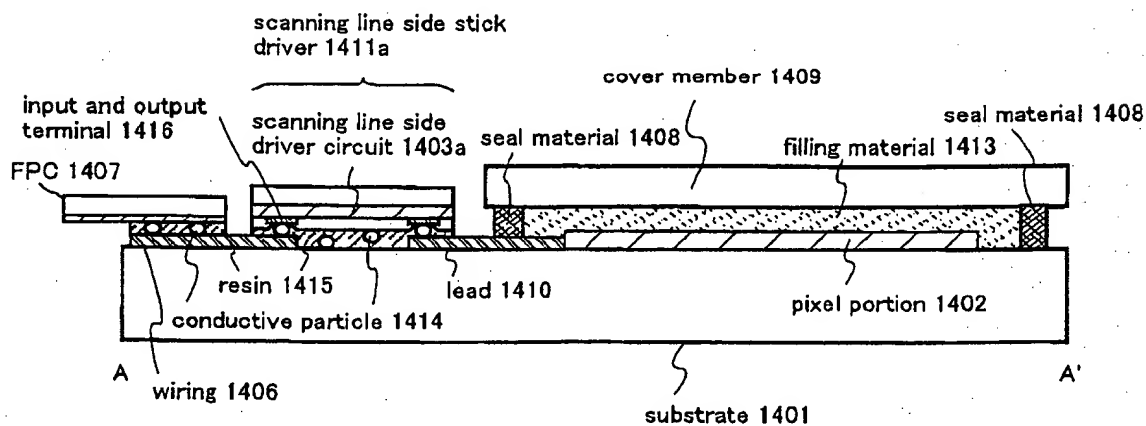


Fig. 15(A)

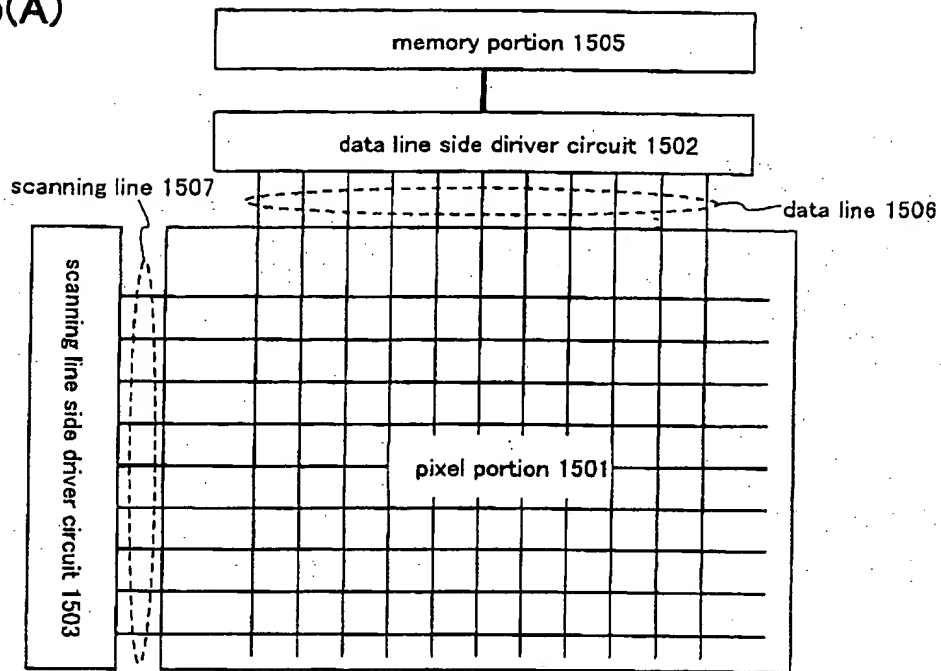
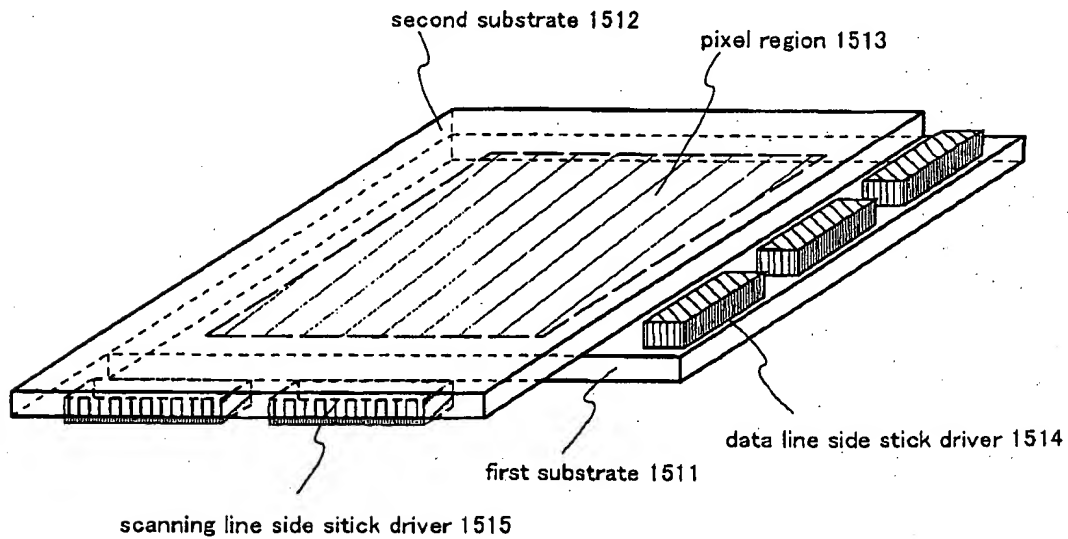


Fig. 15(B)



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[Fig. 16]

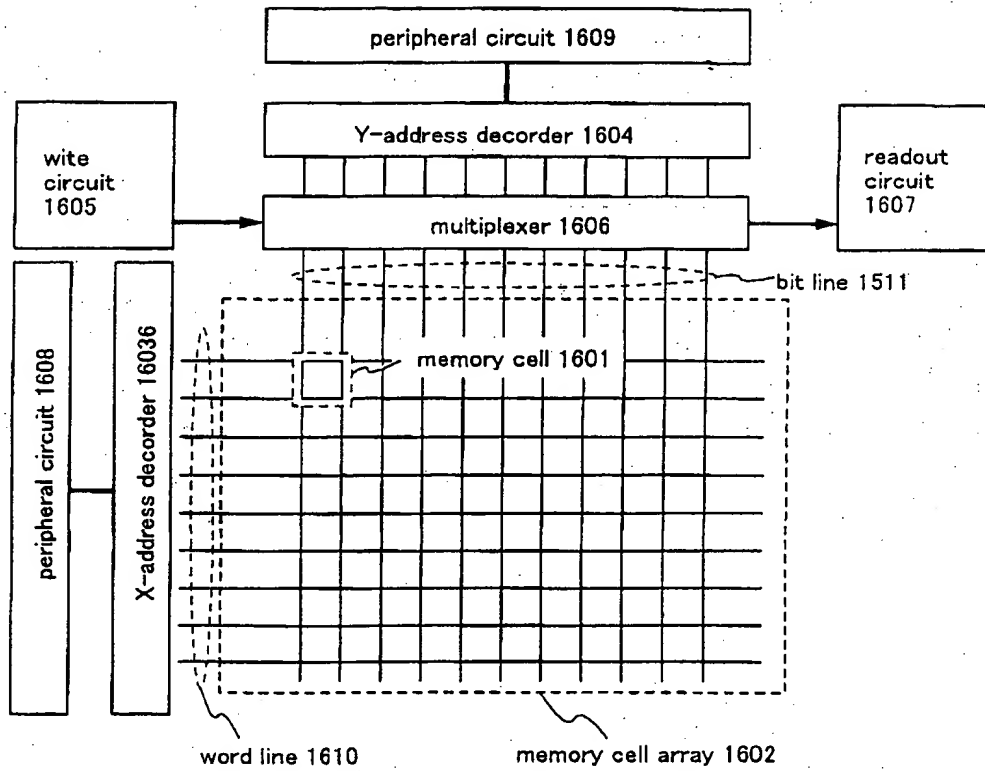


FIG. 16

Fig. 17(A)

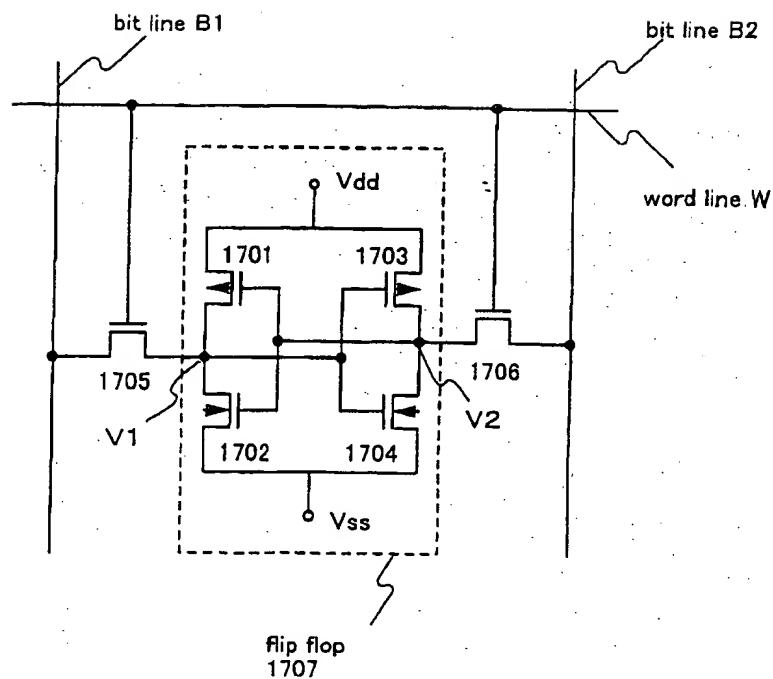
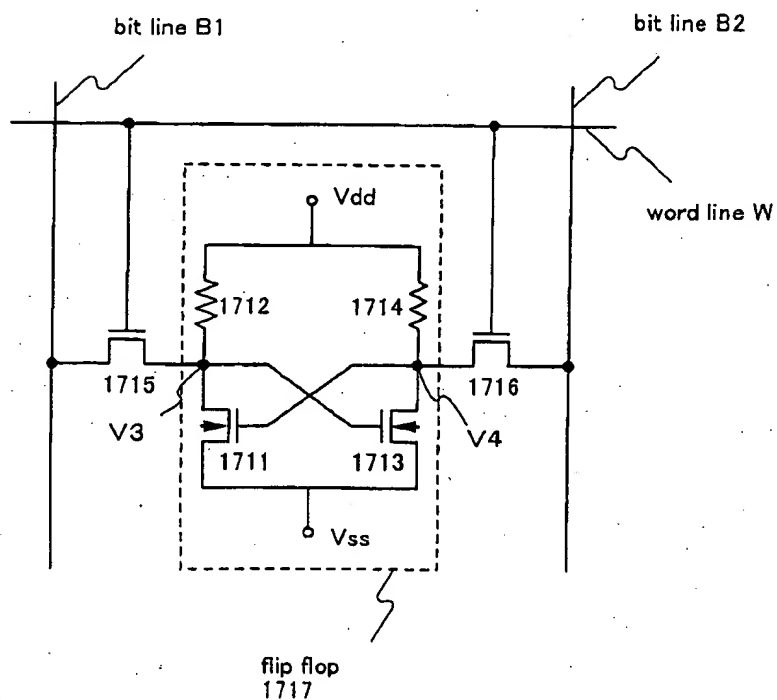


Fig. 17(B)



[Fig. 18]

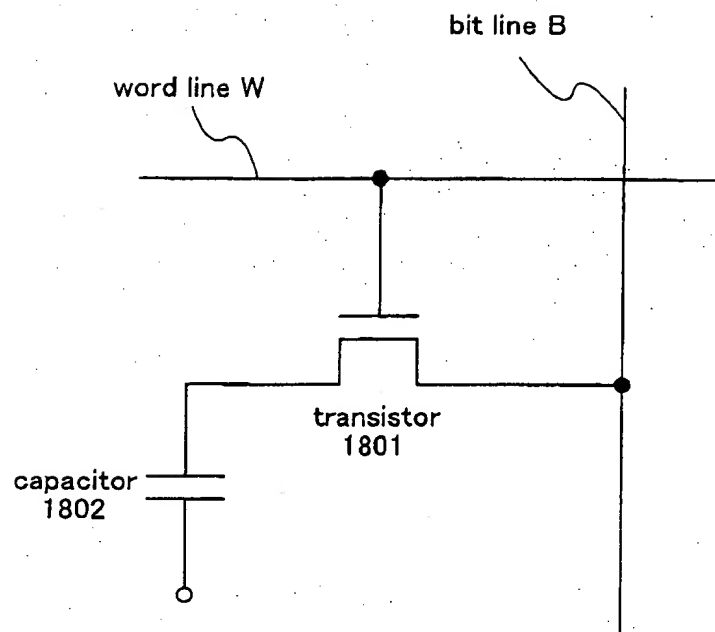
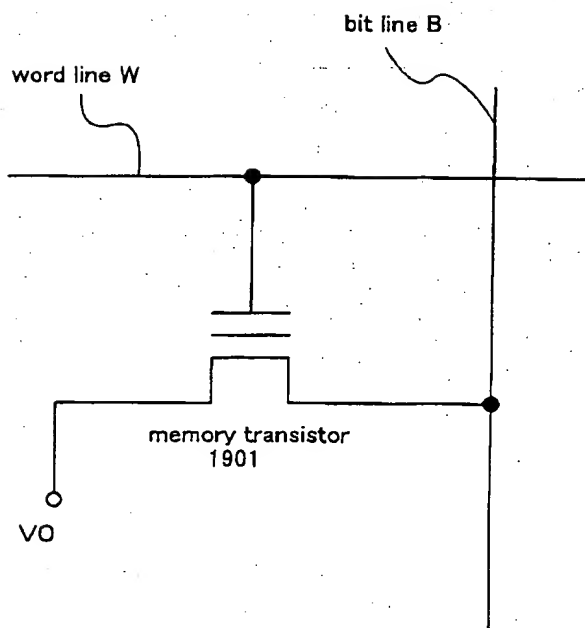


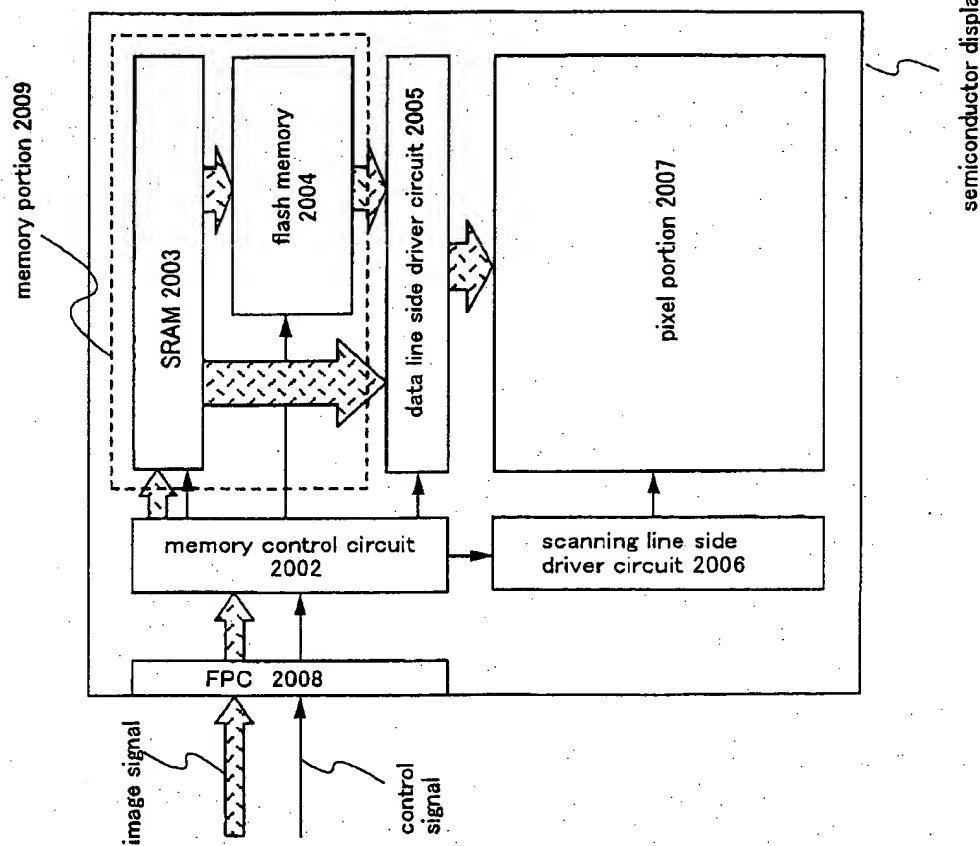
FIG. 18

[Fig. 19]

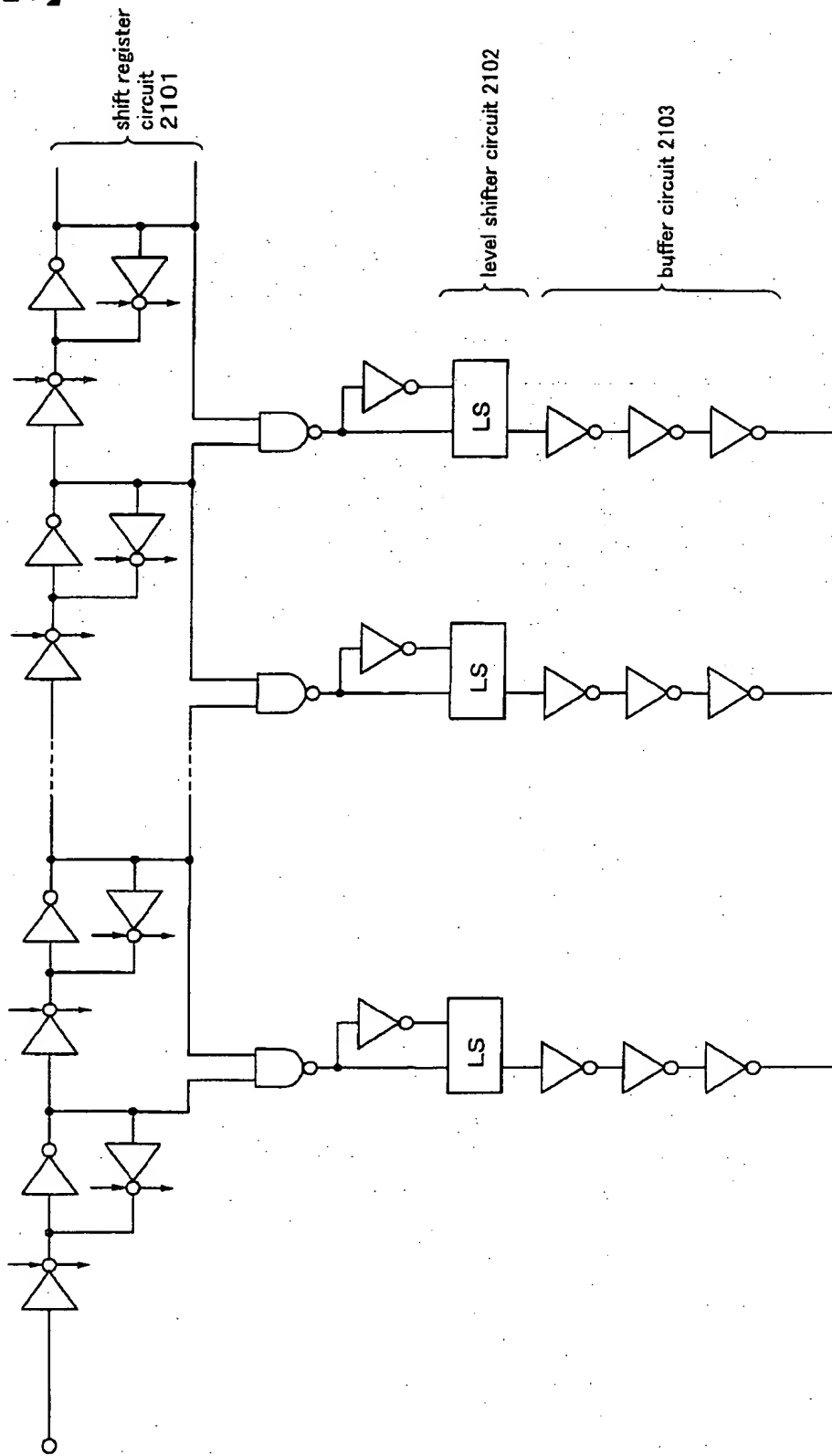


095143-100301

【Fig. 20】



【Fig. 21】



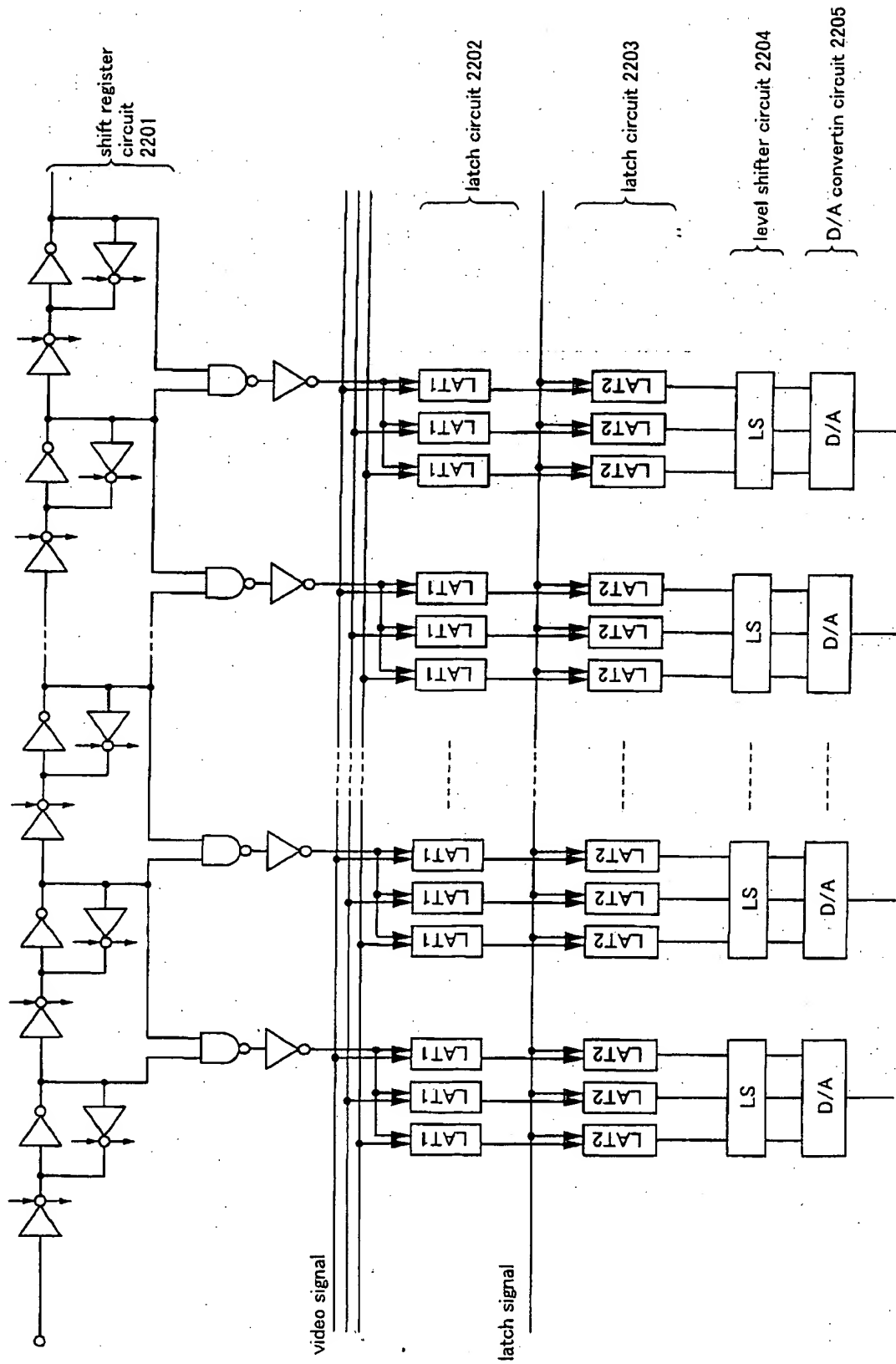


Fig. 22

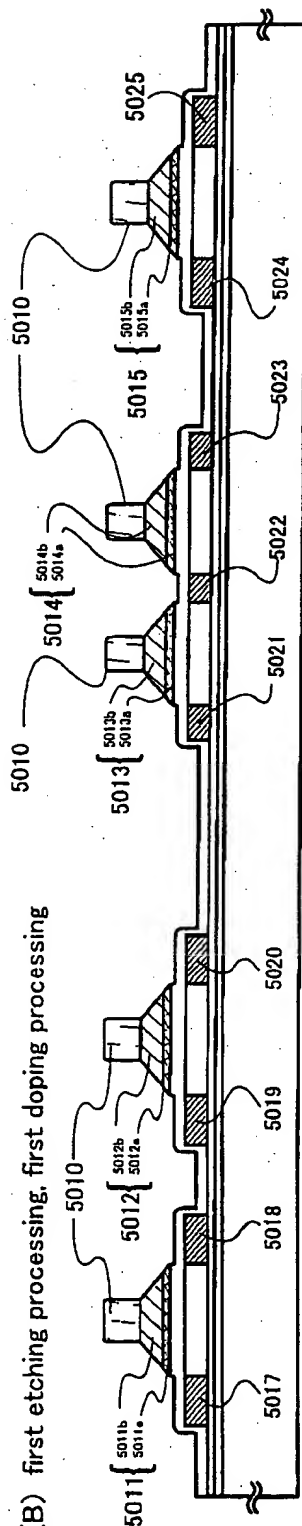
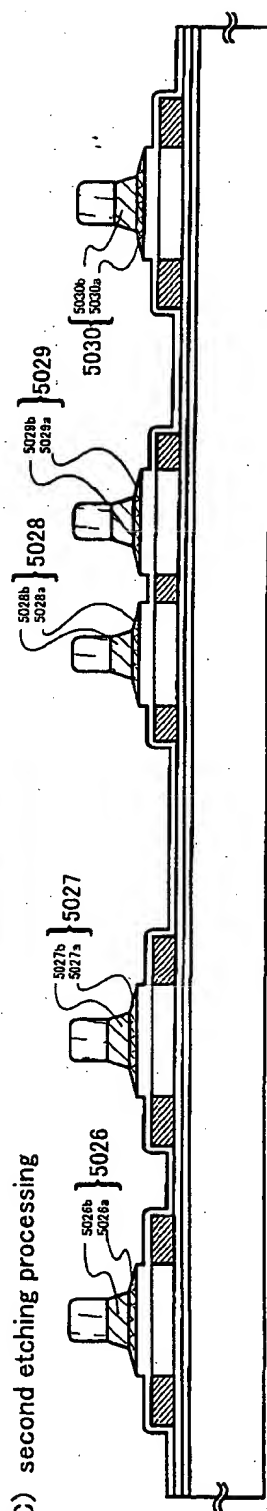


Fig. 23(C) second etching processing



- 5001 : substrate
5002 : base film
5003 ~ 5006 : semiconductor layer
5007 : gate insulating film
5008 : first conductive film
5009 : second conductive film
5010 : resist mask
5011 ~ 5015 : first shaped
conductive layer
5011a ~ 5015a : first conductive layer
5011b ~ 5015b : second conductive layer
5017 ~ 5025 : first impurity region
5026 ~ 5030 : second shaped
conductive layer
5026a ~ 5030a : first conductive layer
5026b ~ 5030b : second conductive layer

Fig. 24(A) second doping processing

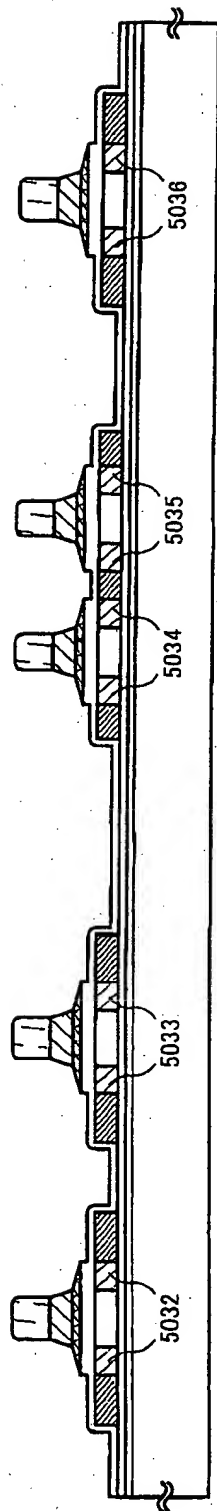


Fig. 24(B) third etching processing

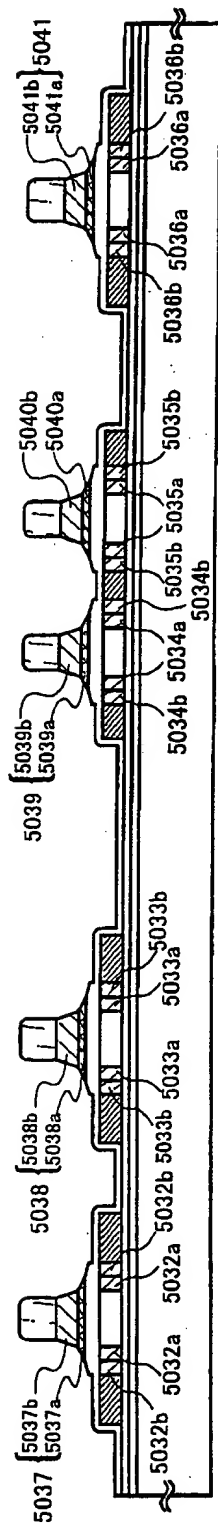
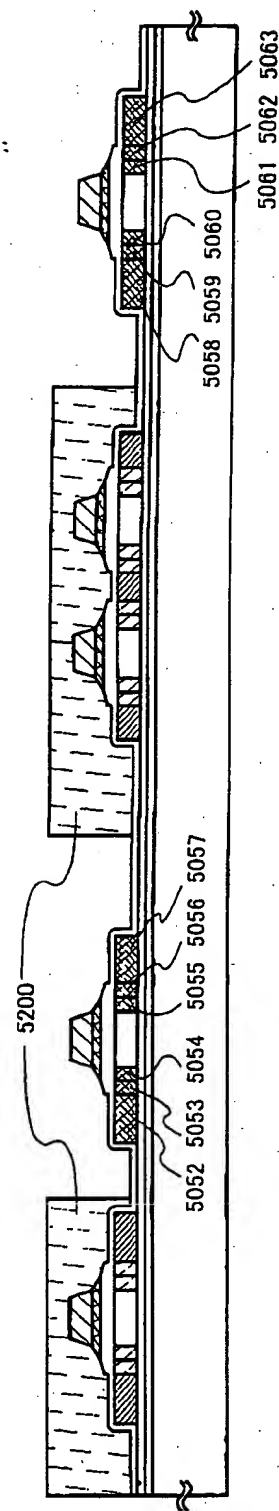


Fig. 24(C) third doping processing



5032~5036 : second impurity region
5032a~5036a : third impurity region
5032b~5036b : fourth impurity region

5037~5041 : third shaped conductive layer
5052~5063 : fifth impurity region
5200 : resist mask

formation of first, second interlayer insulating films and wiring formation

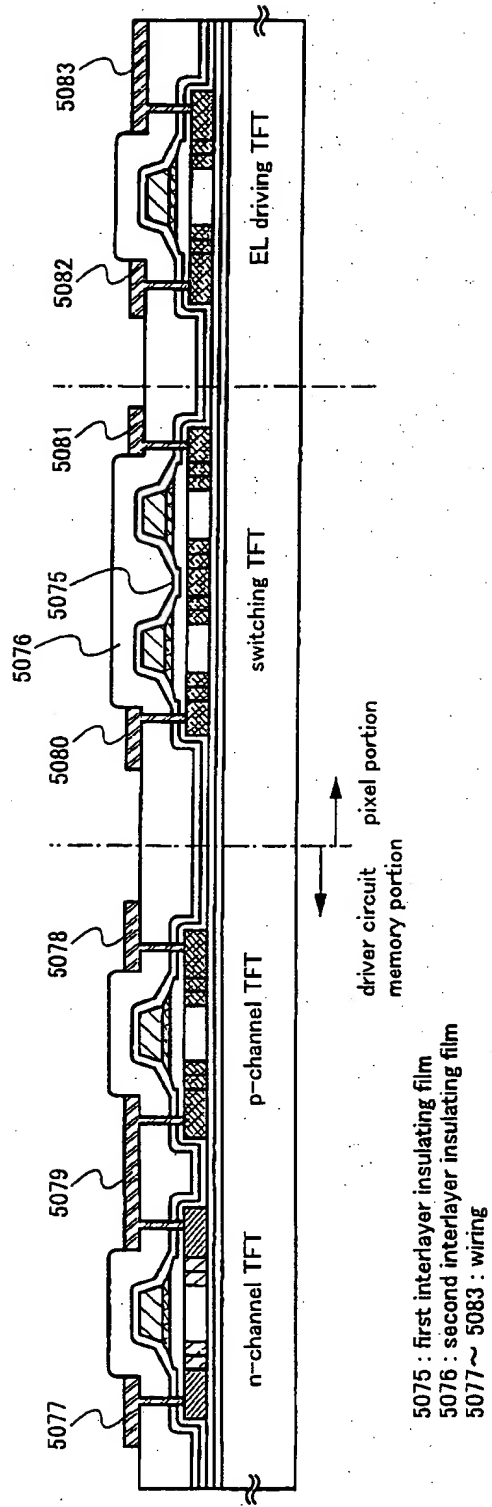
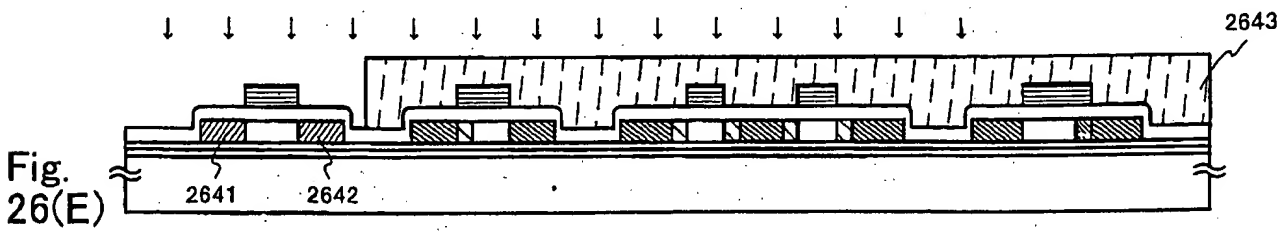
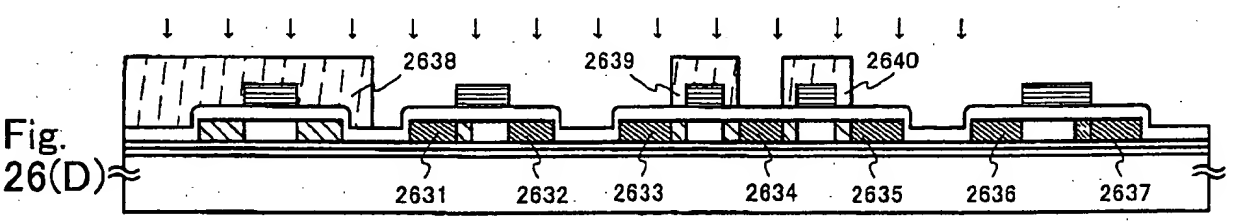
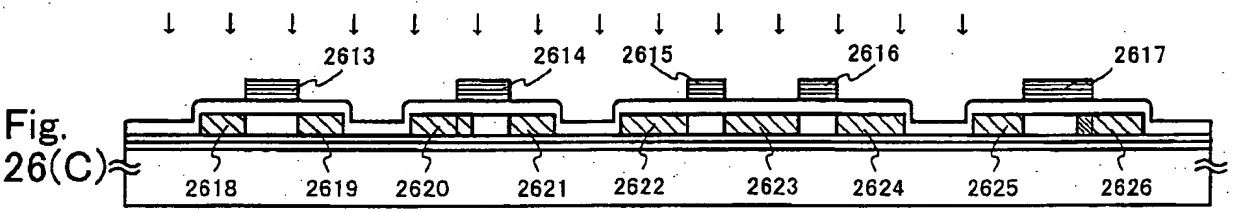
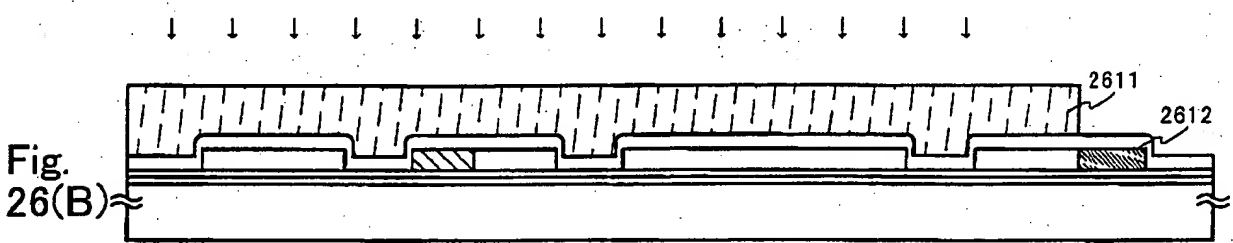
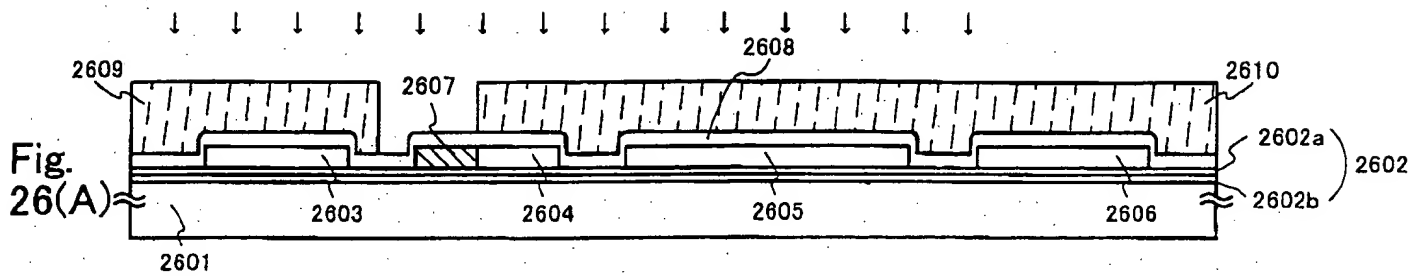


Fig. 25

FIG. 26(A) - FIG. 26(E)



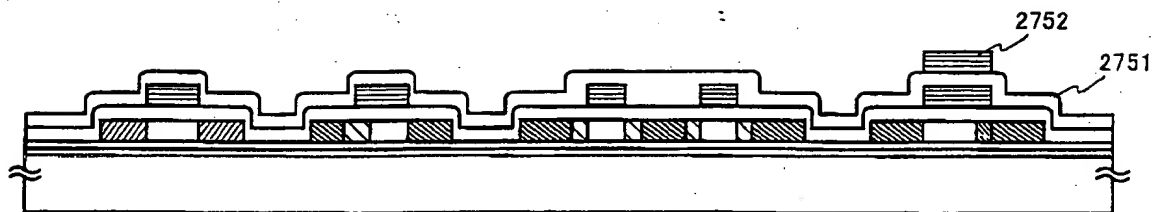


Fig.27(A)

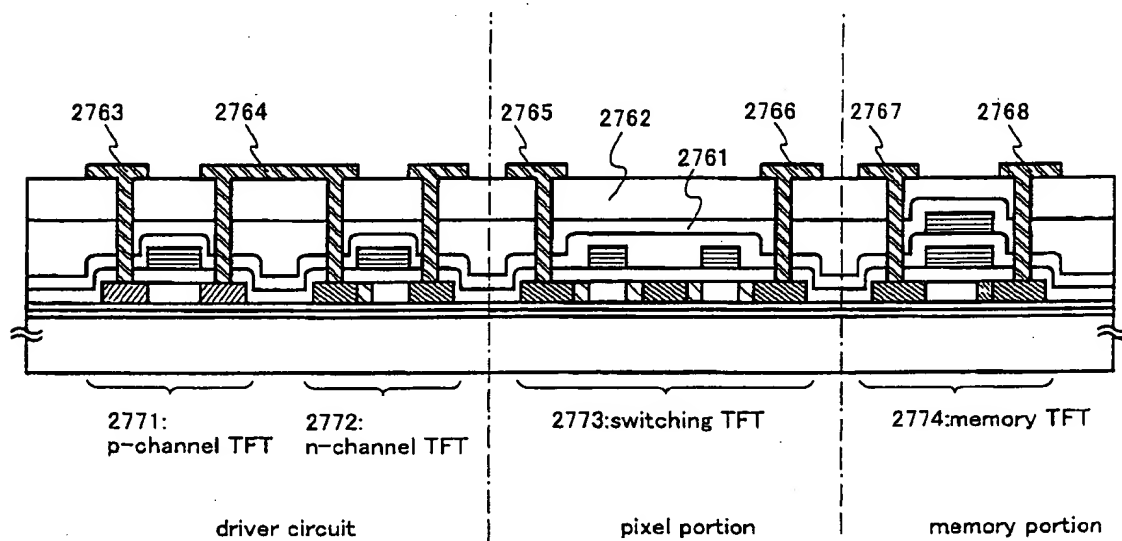


Fig.27(B)

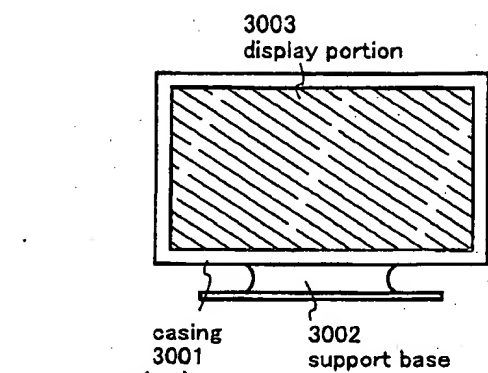


Fig. 28(A)

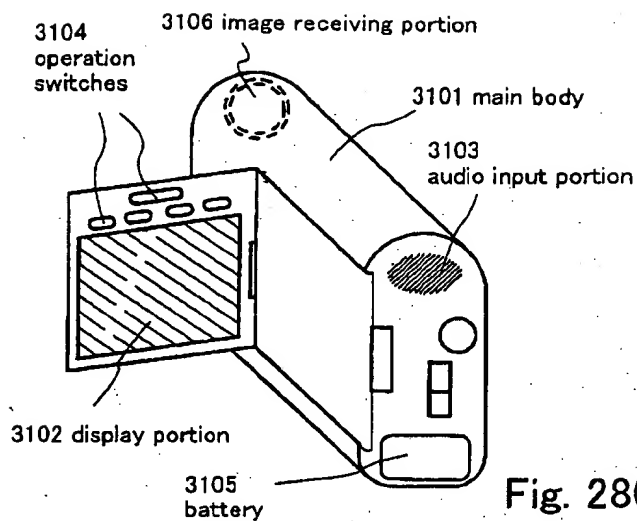


Fig. 28(B)

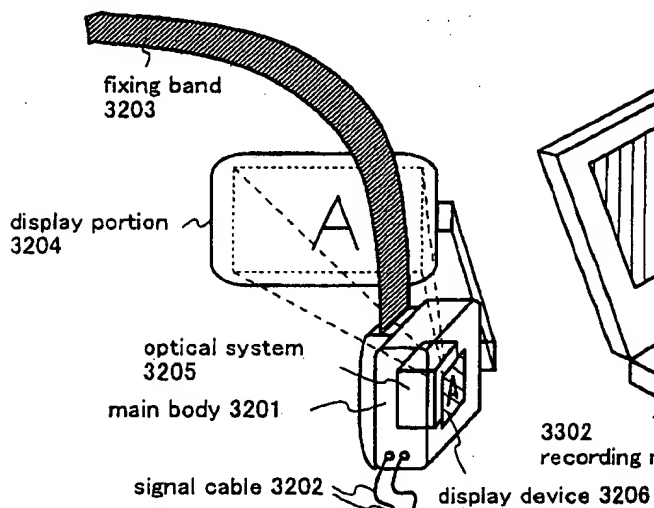


Fig. 28(C)

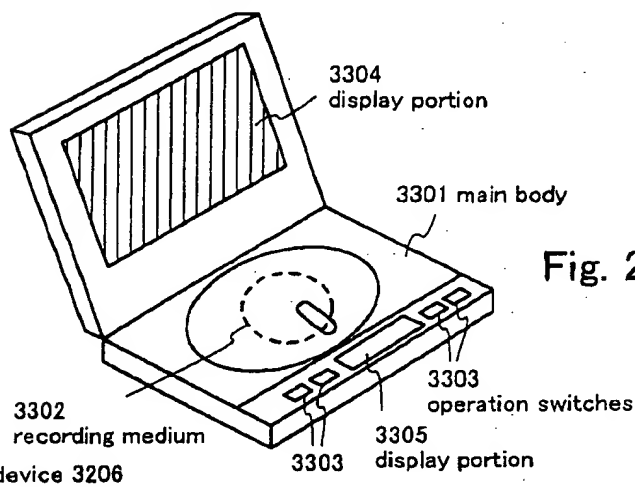


Fig. 28(D)

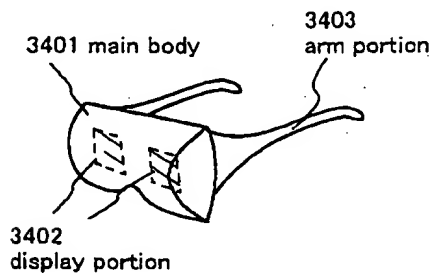


Fig. 28(E)

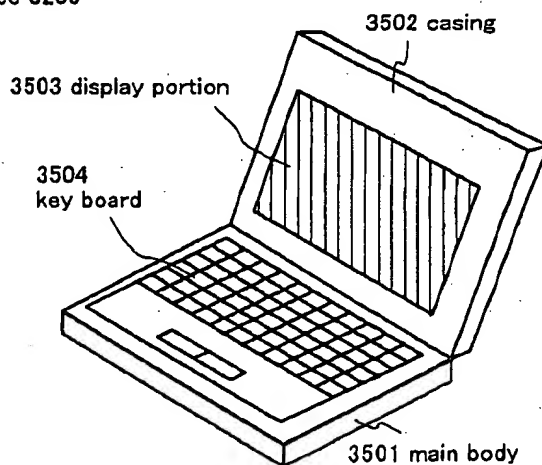


Fig. 28(F)

FOOT-CHTSB60

FIG. 29(A)

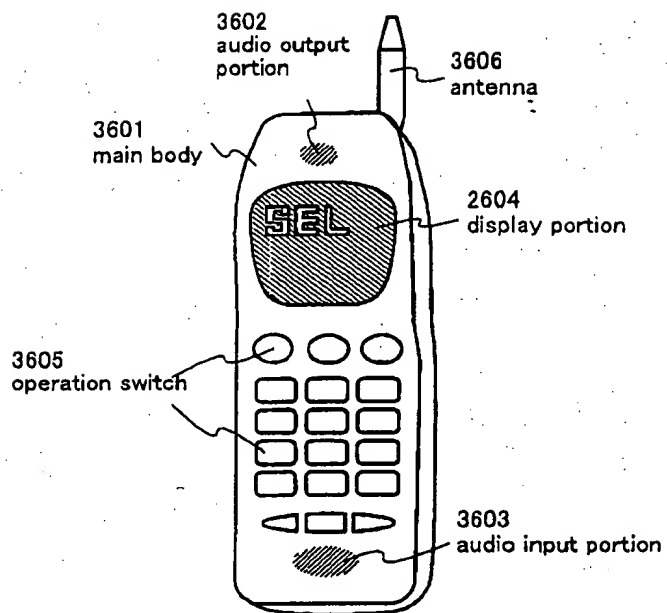


Fig. 29(A)

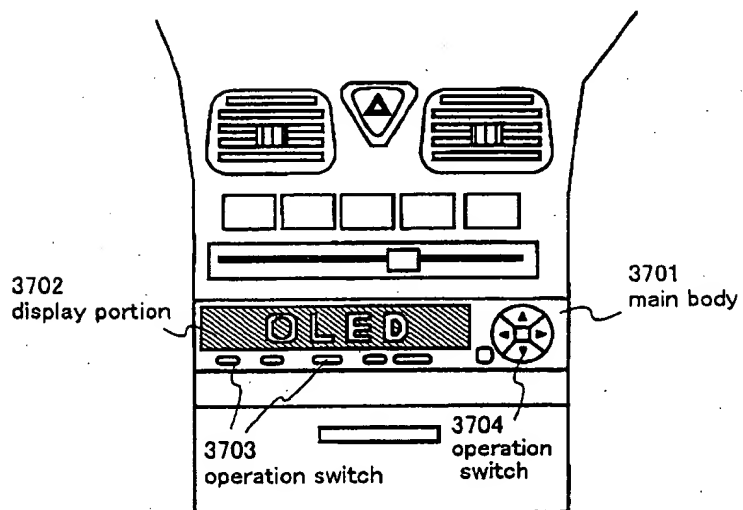


Fig. 29(B)